

January 2009

# **FDP8440**

# N-Channel PowerTrench® MOSFET

**40V, 277A, 2.2m**Ω

#### **Features**

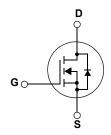
- $R_{DS(on)}$  = 1.64m $\Omega$  (Typ.)@  $V_{GS}$  = 10V,  $I_D$  = 80A
- $Q_{g(tot)} = 345nC (Typ.)@V_{GS} = 10V$
- Low Miller Charge
- Low Q<sub>RR</sub> Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- RoHS Compliant



## **Application**

- · Automotive Engine Control
- · Powertrain Management
- · Motors, Solenoids
- · Electronic Steering
- · Integrated Starter/ Alternator
- Distributed Power Architectures and VRMs
- · Primary Switch for 12V Systems





## MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol		Ratings	Units	
V <sub>DSS</sub>	Drain to Source Voltage	Drain to Source Voltage		
V <sub>GSS</sub>	Gate to Source Voltage		±20	V
I <sub>D</sub>	Drain Current	- Continuous (T <sub>C</sub> = 25°C, Silicon Limited) - Continuous (T <sub>C</sub> = 100°C, Silicon Limited) - Continuous (T <sub>C</sub> = 25°C, Package Limited)	277* 196* 100	А
I <sub>DM</sub>	Drain Current	- Pulsed (Note 1)	500	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		1682	mJ
P <sub>D</sub> Power Dissipation	$(T_C = 25^{\circ}C)$	306	W	
	Power Dissipation	- Derate above 25°C	2.04	W/°C
T <sub>J,</sub> T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +175	°C
TL	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C

<sup>\*</sup>Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 100A.

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.49	°C/W
$R_{\theta CS}$	Thermal Resistance, Case to Sink (Typ.)	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient 62.5		°C/W

# **Package Marking and Ordering Information**

<b>Device Marking</b>	Device	Package	Reel Size	Tape Width	Quantity
FDP8440	FDP8440	TO-220	N/A	N/A	50units

# **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Conditions		Min	Тур	Max	Units
Off Charac	teristics	1		1			
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA		40			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 32V				1	μА
		V <sub>GS</sub> = 0V	T <sub>C</sub> = 150°C			250	μА
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = ±20V				±100	nA
On Charac	teristics	- 1					
V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		1		3	V
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 80A		1.88	2.4	mΩ	
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 80A			1.64		2.2
		$V_{GS} = 10V, I_D = 80A,$ $T_C = 175^{\circ}C$		3.00	4.4		
Dynamic C	haracteristics			•			
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz			18600	24740	pF
C <sub>oss</sub>	Output Capacitance				1840	2450	pF
C <sub>rss</sub>	Reverse Transfer Capacitance				1400	2100	pF
$R_G$	Gate Resistance	V <sub>GS</sub> = 0.5V, f = 1MHz			1.1		Ω
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>GS</sub> = 0V to 10V			345	450	nC
Q <sub>g(2)</sub>	Threshold Gate Charge	V <sub>GS</sub> = 0V to 2V	$V_{DD} = 20V$		32.5		nC
Q <sub>gs</sub>	Gate to Source Gate Charge		I <sub>D</sub> = 80A		49		nC
Q <sub>gs2</sub>	Gate Charge Threshold to Plateau		$I_g = 1.0 \text{mA}$		16.5		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge				74		nC
Switching	Characteristics (V <sub>GS</sub> = 10V)						
t <sub>ON</sub>	Turn-On Time				175	360	ns
t <sub>d(on)</sub>	Turn-On Delay Time				43	95	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 20V, I_D = 80A$ $V_{GS} = 10V, R_{GEN} = 7\Omega$	$V_{DD} = 20V, I_D = 80A$ $V_{CD} = 10V, R_{CD} = 70$		130	275	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	- VGS 101, NGEN 122			435	875	ns
t <sub>f</sub>	Fall Time				290	590	ns
t <sub>OFF</sub>	Turn-Off Time				730	1470	ns
	ce Diode Characteristics and Maximu	ım Ratings		1		ı	ı
	Source to Drain Diode Voltage	I <sub>SD</sub> = 80A				1.25	V
$V_{SD}$		I <sub>SD</sub> = 40A				1.0	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> = 75A, dI <sub>SD</sub> /dt = 100A/μs			59		ns
Q <sub>RR</sub>	Reverse Recovery Charge	$I_{SD} = 75A$ , $dI_{SD}/dt = 100$	0A/μs		77		nC
					1		

#### NOTES

<sup>1:</sup> Pulse width limited by maximum junction temperature.

<sup>2:</sup> Starting T  $_{J}$  = 25°C, L = 1mH, I  $_{AS}$  = 58A, V  $_{DD}$  = 36V, V  $_{GS}$  = 10V.

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

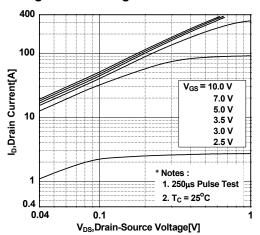


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

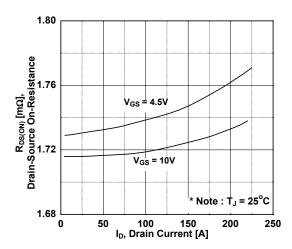


Figure 5. Capacitance Characteristics

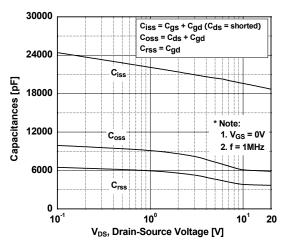


Figure 2. Transfer Characteristics

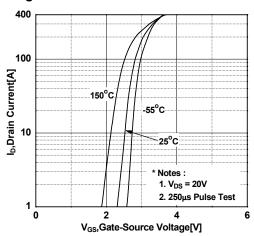


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

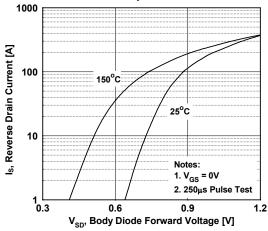
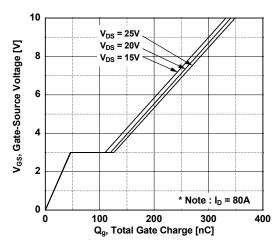


Figure 6. Gate Charge Characteristics



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

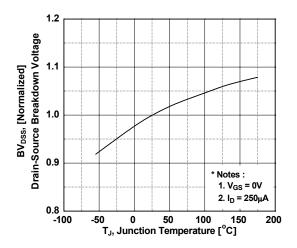
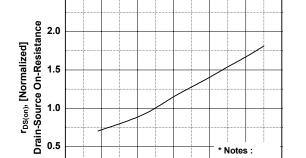


Figure 9. Unclamped Inductive Switching Capability



1. V<sub>GS</sub> = 10V

2. I<sub>D</sub> = 80A

150

200

Figure 8. On-Resistance Variation

2.5

-100

-50

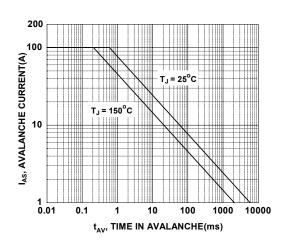
vs. Temperature

Figure 10. Safe Operating Area

50

T<sub>J</sub>, Junction Temperature [°C]

100



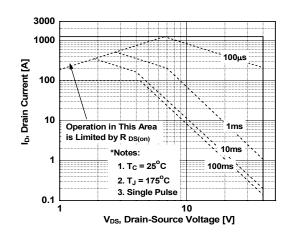
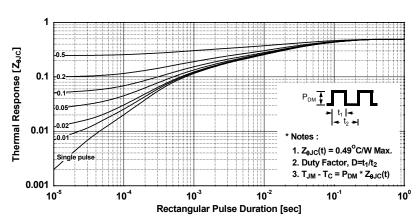
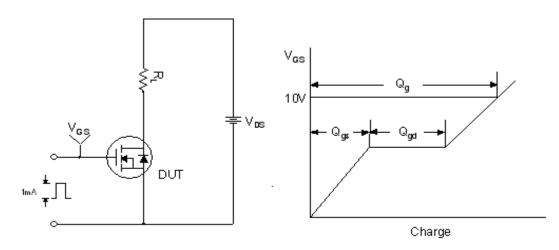


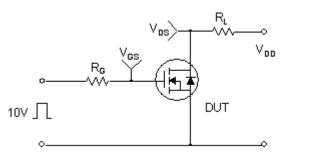
Figure 11. Transient Thermal Response Curve

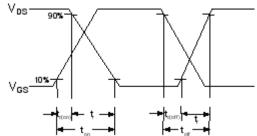


## **Gate Charge Test Circuit & Waveform**

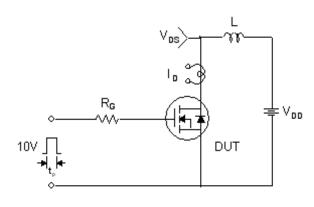


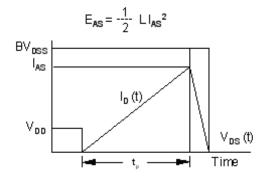
### **Resistive Switching Test Circuit & Waveforms**



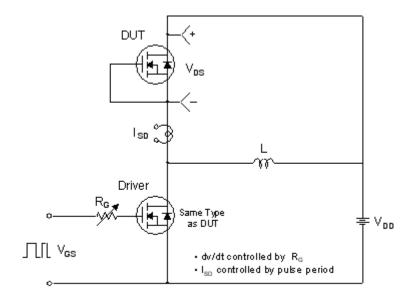


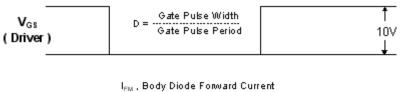
## **Unclamped Inductive Switching Test Circuit & Waveforms**

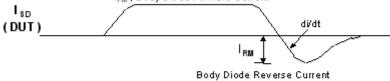


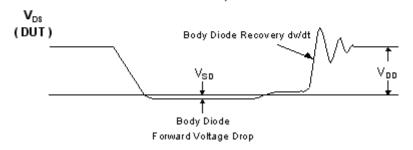


## Peak Diode Recovery dv/dt Test Circuit & Waveforms



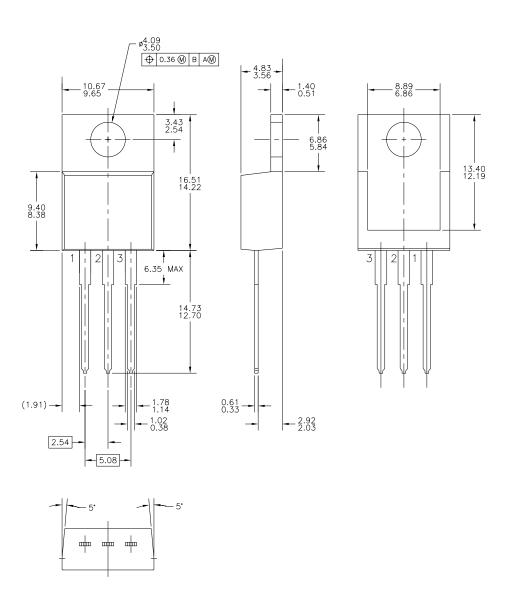






# **Mechanical Dimensions**

# TO-220







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